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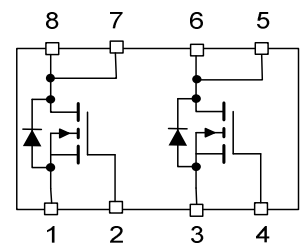
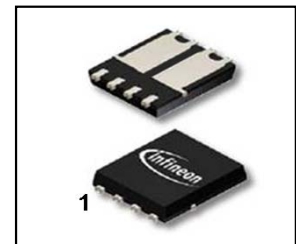
**OptiMOS® Power-Transistor**

**Product Summary**

$V_{DS}$	55	V
$R_{DS(on),max}^{4)}$	50	mΩ
$I_D$	20	A

**Features**

- Dual N-channel Logic Level - Enhancement mode
- AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green Product (RoHS compliant)
- 100% Avalanche tested
- Feasible for automatic optical inspection (AOI)

**PG-TDSON-8-10**


Type	Package	Marking
IPG20N06S2L-50A	PG-TDSON-8-10	2N06L50

**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current one channel active <sup>2)</sup>	$I_D$	$T_C=25\text{ °C}$ , $V_{GS}=10\text{ V}^{1)}$	20	A
		$T_C=100\text{ °C}$ , $V_{GS}=10\text{ V}$	16	
Pulsed drain current <sup>2)</sup> one channel active	$I_{D,pulse}$	-	80	
Avalanche energy, single pulse <sup>2, 4)</sup>	$E_{AS}$	$I_D=10\text{ A}$	60	mJ
Avalanche current, single pulse <sup>4)</sup>	$I_{AS}$	-	15	A
Gate source voltage	$V_{GS}$	-	±20	V
Power dissipation one channel active	$P_{tot}$	$T_C=25\text{ °C}$	51	W
Operating and storage temperature	$T_j$ , $T_{stg}$	-	-55 ... +175	°C
IEC climatic category; DIN IEC 68-1	-	-	55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
<b>Thermal characteristics<sup>2)</sup></b>						
Thermal resistance, junction - case	$R_{thJC}$	-	-	-	2.9	K/W
SMD version, device on PCB	$R_{thJA}$	minimal footprint	-	100	-	
		6 cm <sup>2</sup> cooling area <sup>3)</sup>	-	60	-	

**Electrical characteristics**, at  $T_j=25\text{ °C}$ , unless otherwise specified

**Static characteristics**

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$	55	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_D=19\text{ }\mu\text{A}$	1.2	1.6	2.0	
Zero gate voltage drain current <sup>4)</sup>	$I_{DSS}$	$V_{DS}=55\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=25\text{ °C}$	-	0.01	1	$\mu\text{A}$
		$V_{DS}=55\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=125\text{ °C}^{2)}$	-	1	100	
Gate-source leakage current <sup>4)</sup>	$I_{GSS}$	$V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$	-	1	100	nA
Drain-source on-state resistance <sup>4)</sup>	$R_{DS(on)}$	$V_{GS}=4.5\text{ V}$ , $I_D=10\text{ A}$	-	50	60	m $\Omega$
		$V_{GS}=10\text{ V}$ , $I_D=15\text{ A}$	-	39	50	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics<sup>2)</sup>**

Input capacitance <sup>4)</sup>	$C_{iss}$	$V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$ $f=1\text{ MHz}$	-	430	560	pF
Output capacitance <sup>4)</sup>	$C_{oss}$		-	120	160	
Reverse transfer capacitance <sup>4)</sup>	$C_{rss}$		-	45	68	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=27.5\text{ V},$ $V_{GS}=10\text{ V}, I_D=20\text{ A},$ $R_G=11\ \Omega$	-	2	-	ns
Rise time	$t_r$		-	3	-	
Turn-off delay time	$t_{d(off)}$		-	15	-	
Fall time	$t_f$		-	10	-	

**Gate Charge Characteristics<sup>2, 4)</sup>**

Gate to source charge	$Q_{gs}$	$V_{DD}=44\text{ V}, I_D=20\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	1.5	2	nC
Gate to drain charge	$Q_{gd}$		-	4.6	6.9	
Gate charge total	$Q_g$		-	13	17	
Gate plateau voltage	$V_{plateau}$		-	3.7	-	V

**Reverse Diode**

Diode continuous forward current <sup>2)</sup> one channel active	$I_S$	$T_C=25\text{ }^\circ\text{C}$	-	-	20	A
Diode pulse current <sup>2)</sup> one channel active	$I_{S,pulse}$		-	-	80	
Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=15\text{ A},$ $T_J=25\text{ }^\circ\text{C}$	-	1.0	1.3	V
Reverse recovery time <sup>2)</sup>	$t_{rr}$	$V_R=27.5\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	25	-	ns
Reverse recovery charge <sup>2, 4)</sup>	$Q_{rr}$		-	24	-	nC

<sup>1)</sup> Current is limited by bondwire; with an  $R_{thJC}=2.9\text{ K/W}$  the chip is able to carry 23A at 25°C.

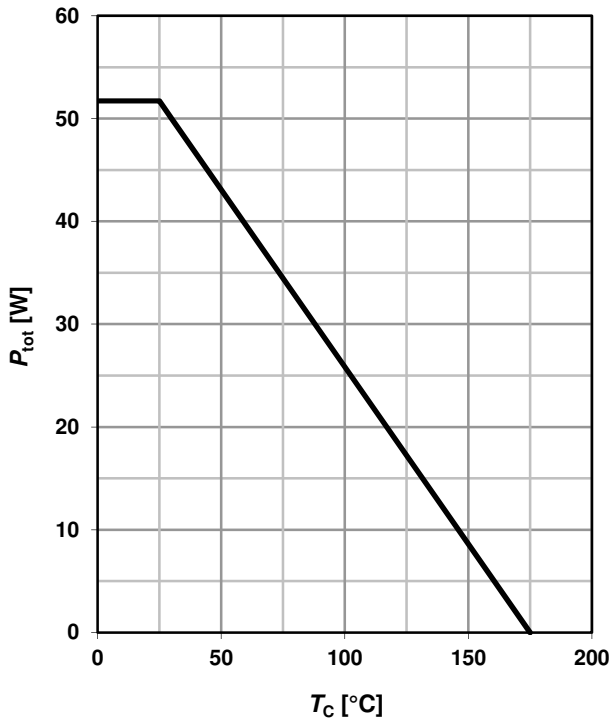
<sup>2)</sup> Specified by design. Not subject to production test.

<sup>3)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

<sup>4)</sup> Per channel

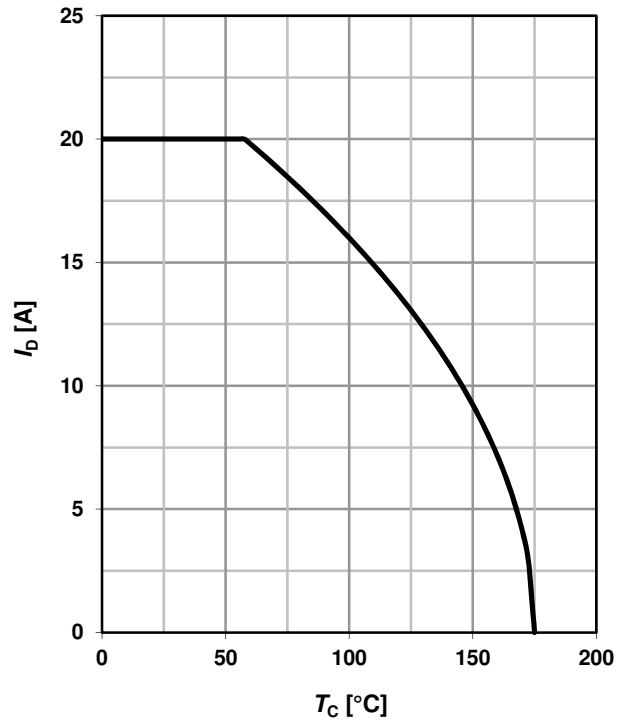
**1 Power dissipation**

$P_{tot} = f(T_C)$ ;  $V_{GS} \geq 6\text{ V}$ ; one channel active



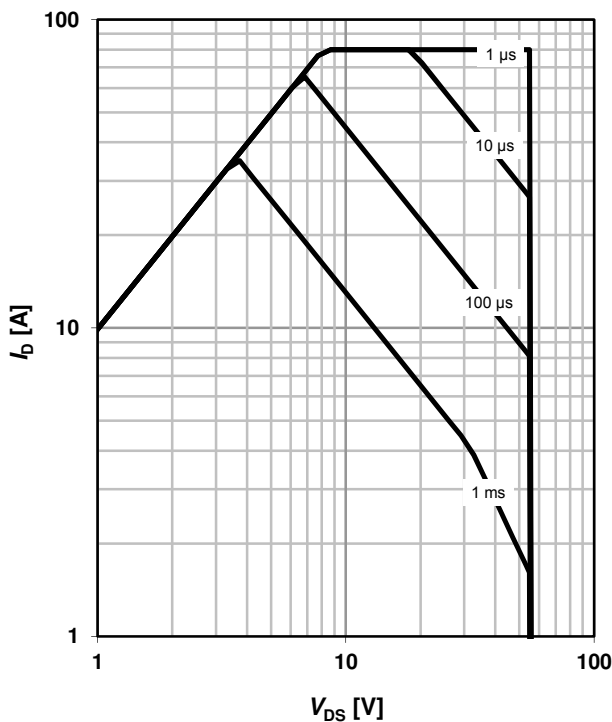
**2 Drain current**

$I_D = f(T_C)$ ;  $V_{GS} \geq 6\text{ V}$ ; one channel active



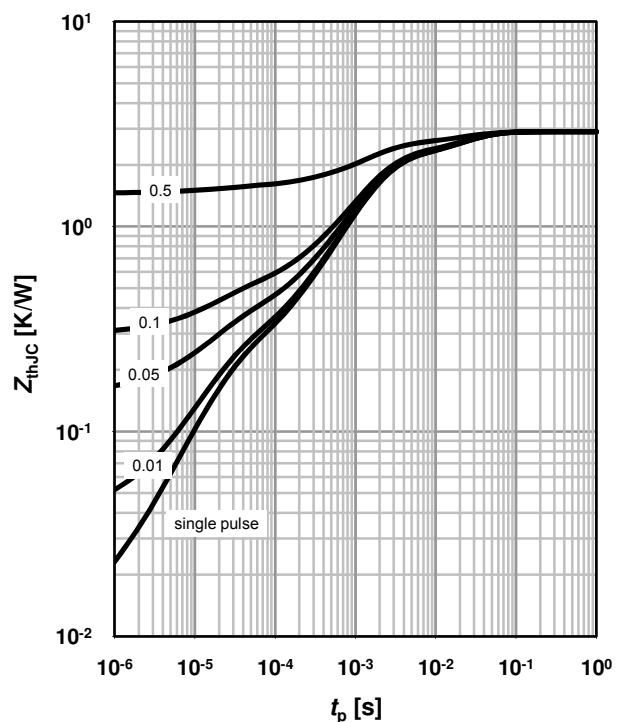
**3 Safe operating area**

$I_D = f(V_{DS})$ ;  $T_C = 25^\circ\text{C}$ ;  $D = 0$ ; one channel active  
parameter:  $t_p$



**4 Max. transient thermal impedance**

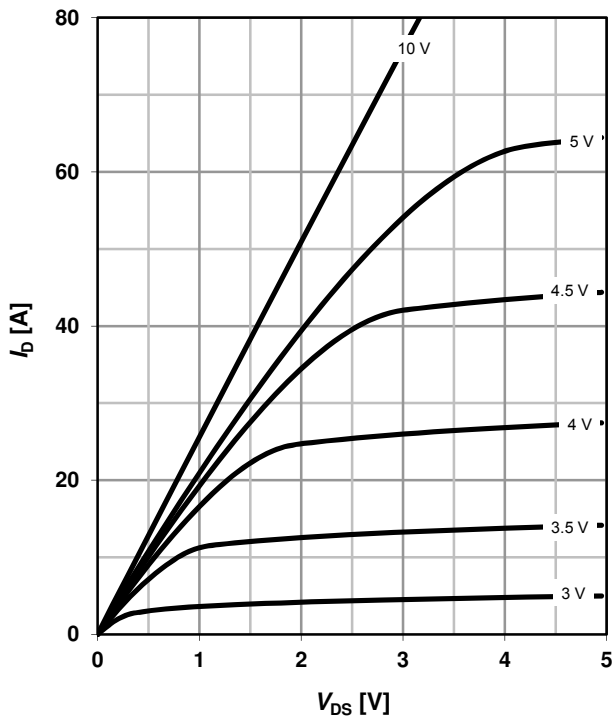
$Z_{thJC} = f(t_p)$   
parameter:  $D = t_p/T$



**5 Typ. output characteristics<sup>4)</sup>**

$I_D = f(V_{DS}); T_j = 25\text{ °C}$

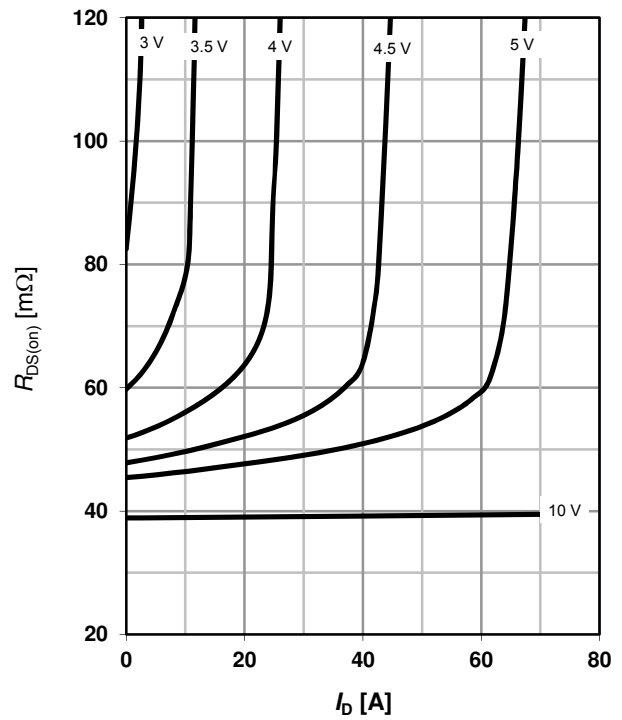
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance<sup>4)</sup>**

$R_{DS(on)} = f(I_D); T_j = 25\text{ °C}$

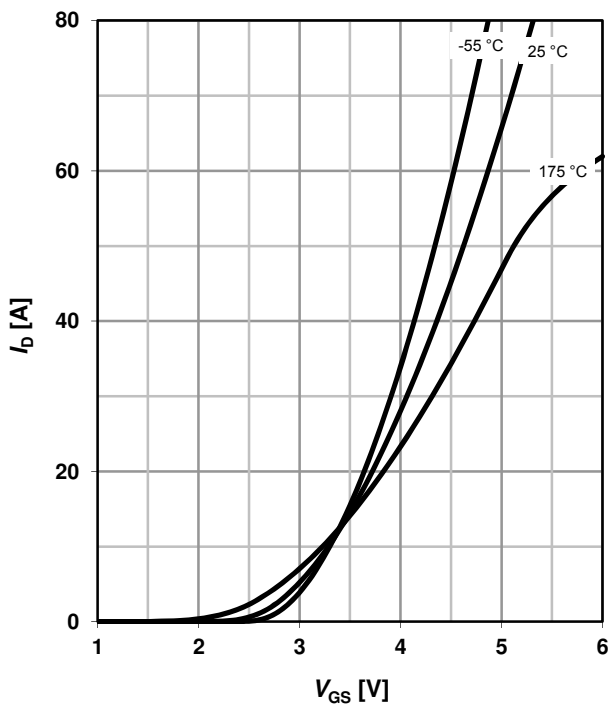
parameter:  $V_{GS}$



**7 Typ. transfer characteristics<sup>4)</sup>**

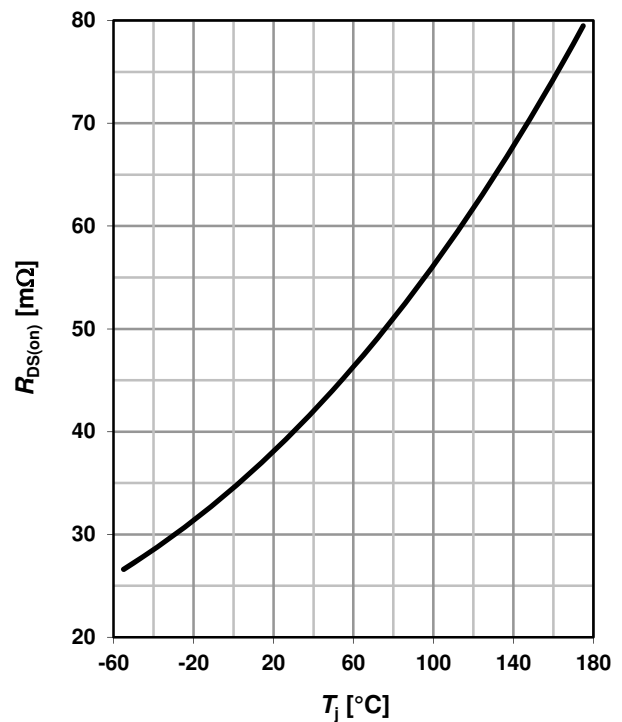
$I_D = f(V_{GS}); V_{DS} = 6V$

parameter:  $T_j$



**8 Typ. drain-source on-state resistance<sup>4)</sup>**

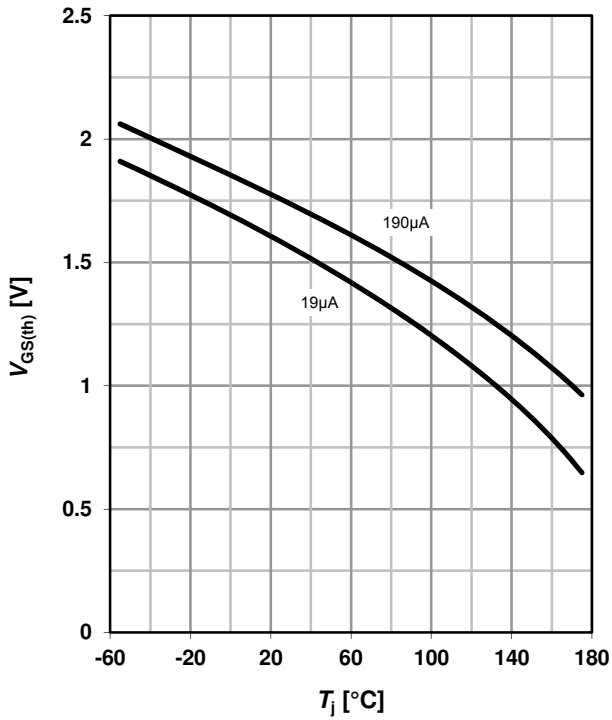
$R_{DS(on)} = f(T_j); I_D = 15\text{ A}; V_{GS} = 10\text{ V}$



**9 Typ. gate threshold voltage**

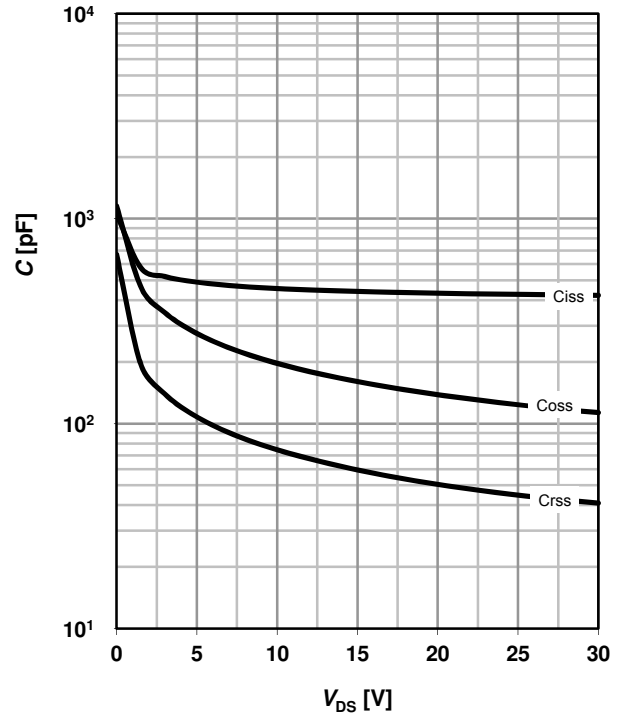
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter:  $I_D$



**10 Typ. Capacitances<sup>4)</sup>**

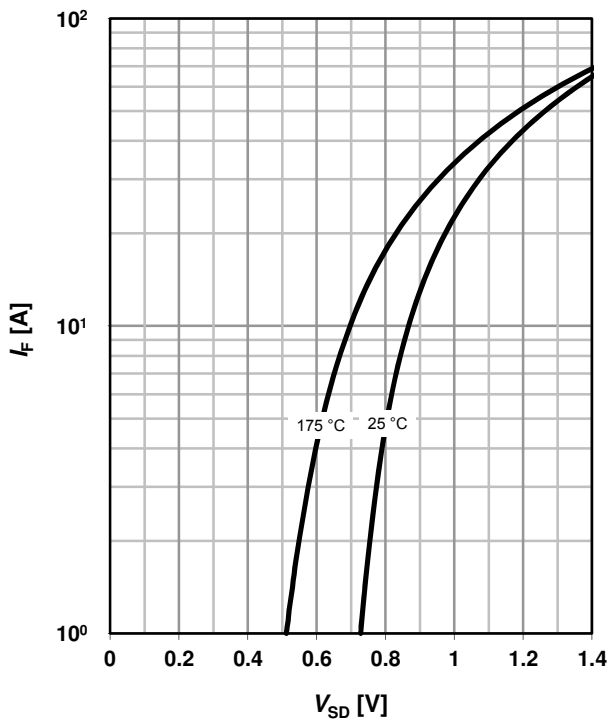
$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$



**11 Typical forward diode characteristics<sup>4)</sup>**

$I_F = f(V_{SD})$

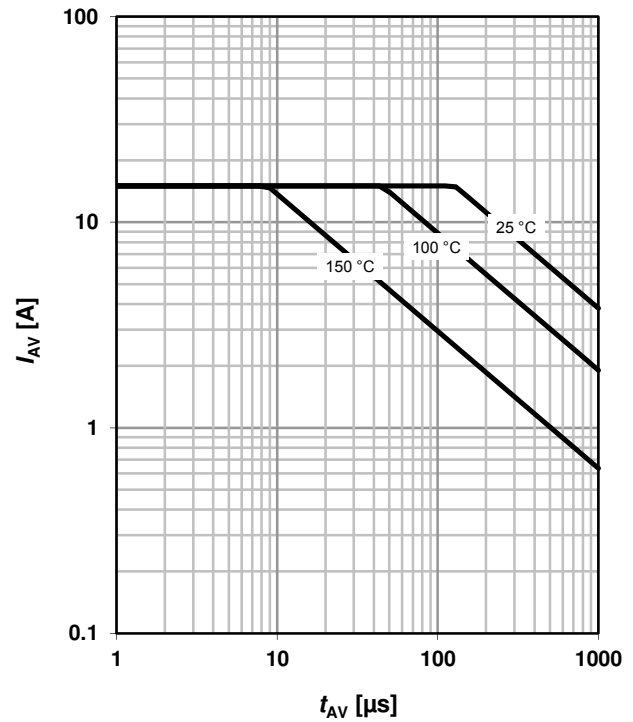
parameter:  $T_j$



**12 Avalanche characteristics<sup>4)</sup>**

$I_{AS} = f(t_{AV})$

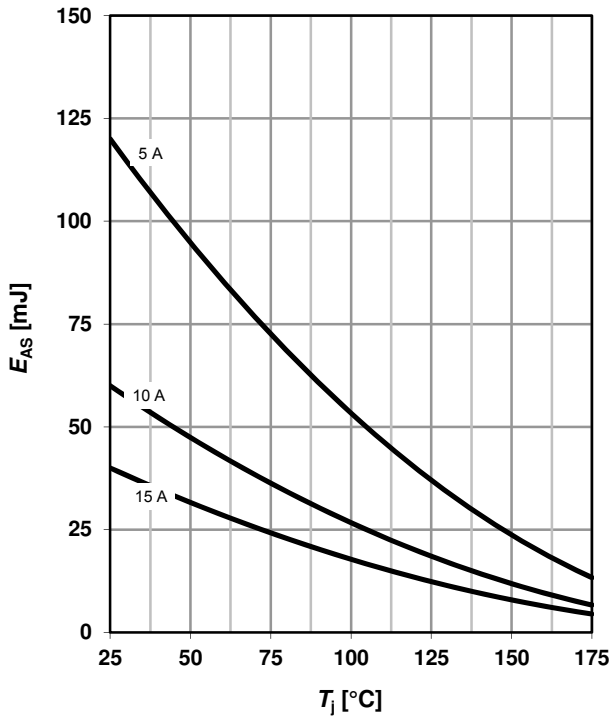
parameter:  $T_{j(start)}$



**13 Avalanche energy<sup>4)</sup>**

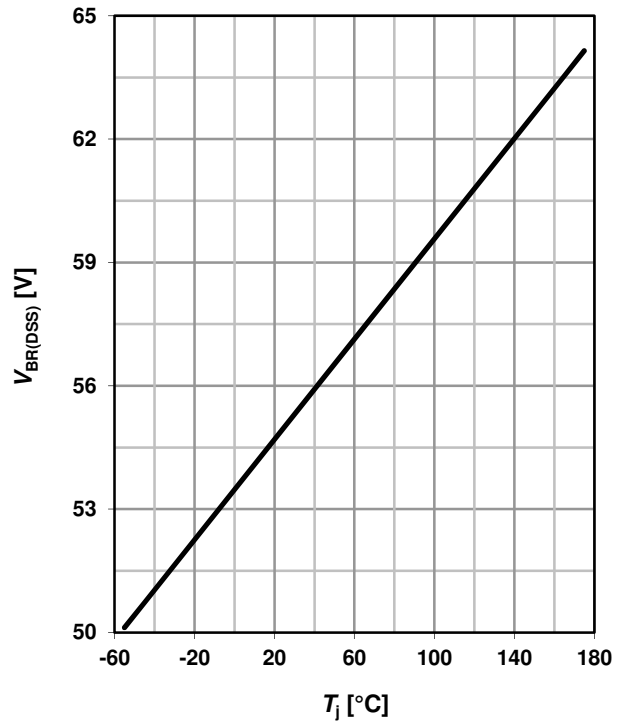
$E_{AS} = f(T_j)$

parameter:  $I_D$



**14 Drain-source breakdown voltage**

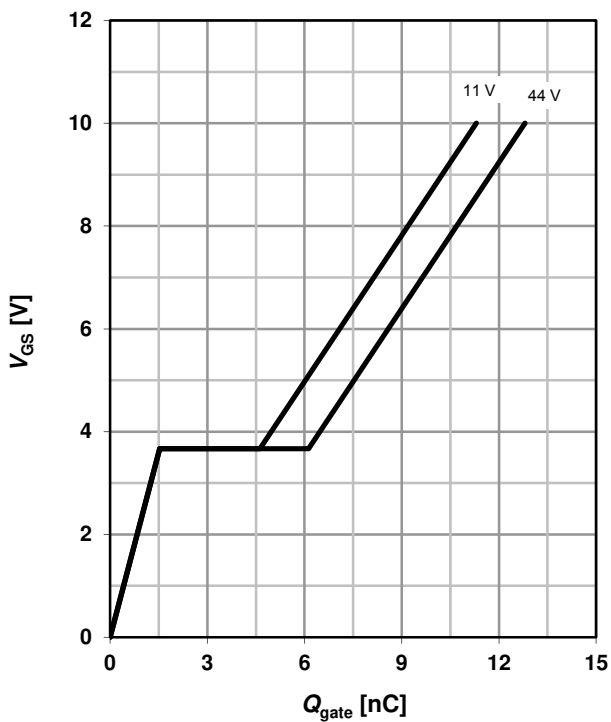
$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$



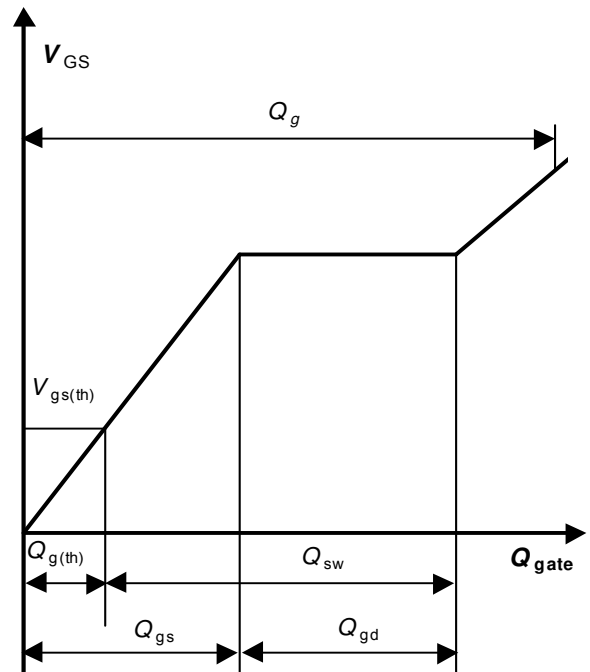
**15 Typ. gate charge<sup>4)</sup>**

$V_{GS} = f(Q_{gate}); I_D = 20 \text{ A pulsed}$

parameter:  $V_{DD}$



**16 Gate charge waveforms**





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If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

## Revision History

Version	Date	Changes
Revision 1.0	14.11.2012	Final Data Sheet